**ON Semiconductor** 

Is Now

# Onsemi

To learn more about onsemi<sup>™</sup>, please visit our website at <u>www.onsemi.com</u>

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# **MOSFET** – Power, N-Channel, SUPERFET<sup>®</sup> III 800 V, 450 mΩ, 11 A

# NTPF450N80S3Z

#### Description

800 V SUPERFET III MOSFET is ON Semiconductor's high performance MOSFET family offering 800 V breakdown voltage.

New 800 V SUPERFET III MOSFET which is optimized for primary switch of flyback converter, enables lower switching losses and case temperature without sacrificing EMI performance thanks to its optimized design. In addition, internal Zener Diode significantly improves ESD capability.

This new family of 800 V SUPERFET III MOSFET enables to make more efficient, compact, cooler and more robust applications because of its remarkable performance in switching power applications such as Laptop adapter, Audio, Lighting, ATX power and industrial power supplies.

#### Features

- Typ.  $R_{DS(on)} = 380 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Qg = 19.3 nC)
- Low Stored Energy in Output Capacitance (Eoss = 2.2 µJ @ 400 V)
- 100% Avalanche Tested
- ESD Improved Capability with Zener Diode
- RoHS Compliant

#### Applications

- Adapters / Chargers
- LED Lighting
- AUX Power
- Audio
- Industrial Power

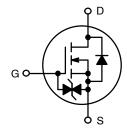


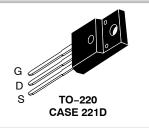
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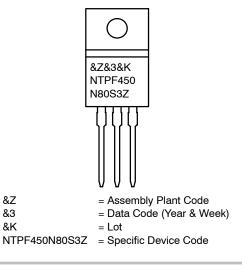
V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX	
800 V	450 m $\Omega$ @ V <sub>GS</sub> = 10 V	11 A	







#### MARKING DIAGRAM



## ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

1

Symbol	Paramete	Value	Unit V		
V <sub>DSS</sub>	Drain-to-Source Voltage	800			
V <sub>GS</sub>	Gate-to-Source Voltage	DC	±20	V	
		AC (f > 1 Hz)	±30	V	
Ι <sub>D</sub>	Drain Current	Continuous (T <sub>C</sub> = 25°C)	11*	А	
		Continuous (T <sub>C</sub> = 100°C)	7*	А	
I <sub>DM</sub>	Drain Current Pulsed (Note 1)		25*	А	
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		32	mJ	
I <sub>AS</sub>	Avalanche Current (Note 2)		1.55	А	
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		0.295	mJ	
dv/dt	MOSFET dv/dt		100	V/ns	
	Peak Diode Recovery dv/dt (Note 3)		10	V/ns	
PD	Power Dissipation $T_{\rm C} = 25^{\circ}{\rm C}$		29.5	W	
		Derate above 25°C	0.236	W/∘C	
T <sub>J</sub> , T <sub>stg</sub>	Operating Junction and Storage Temperature Range		-55 to +150	°C	
ΤL	Lead Temperature for Soldering Purposes (1/8" from Case for 10 seconds)		260	°C	

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
\*Drain current limited by maximum junction temperature
1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. I<sub>AS</sub> = 1.55 A, R<sub>G</sub> = 25 Ω, starting T<sub>J</sub> = 25°C.
3. I<sub>SD</sub> ≤ 2.75 A, di/dt ≤ 200 A/µs, V<sub>DD</sub> ≤ 400 V, starting T<sub>J</sub> = 25°C.

#### **THERMAL CHARACTERISTICS**

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	4.23	°C/W
$R_{ hetaJA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NTPF450N80S3Z	NTPF450N80S3Z	TO-220F	Tube	N/A	N/A	50 Units

#### **ELECTRICAL CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
FF CHARACT	ERISTICS			1		
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	$V_{GS}$ = 0 V, $I_D$ = 1 mA, $T_J$ = 25°C	800	-	-	V
		$V_{GS}$ = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 150°C	900	-	-	V
$\Delta \text{BV}_{\text{DSS}} / \Delta \text{T}_{\text{J}}$	Drain-to-Source Breakdown Voltage Temperature Coefficient			1.1	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μΑ
		$V_{DS} = 640 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	0.8	-	
I <sub>GSS</sub>	Gate-to-Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±1	μΑ
ON CHARACTE	RISTICS					•
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 0.24$ mA	2.2	-	3.8	V
R <sub>DS(on)</sub>	Static Drain-to-Source On Resistance	$V_{GS}$ = 10 V, I <sub>D</sub> = 5.5 A	-	380	450	mΩ
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}$	-	11.8	_	S
YNAMIC CHA	RACTERISTICS		•			
C <sub>iss</sub>	Input Capacitance	$V_{\rm D} = 400 \text{ V}, V_{\rm GS} = 0 \text{ V},$	-	885	-	pF
C <sub>oss</sub>	Output Capacitance	f = 250 kHz	-	15	-	
C <sub>oss(eff.)</sub>	Effective Output Capacitance	$V_{DS} = 0 \text{ V}$ to 400 V, $V_{GS} = 0 \text{ V}$	-	188	-	
C <sub>oss(er.)</sub>	Energy Related Output Capacitance		_	27	-	
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	$V_{DS} = 400 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}, \text{ V}_{GS} = 10 \text{ V}$	-	19.3	_	nC
Q <sub>gs</sub>	Gate-to-Source Charge	(Note 4)	_	4.2	_	
Q <sub>gd</sub>	Gate-to-Drain "Miller" Charge		-	6.6	_	
ESR	Equivalent Series Resistance	f = 1 MHz	-	4.0	-	Ω
	IARACTERISTICS					•
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, \text{ I}_{D} = 5.5 \text{ A},$	-	13.3	-	ns
tr	Turn–On Rise Time	V <sub>GS</sub> = 10 V, R <sub>G</sub> = 4.7 Ω (Note 4)	-	6.7	-	1
t <sub>d(off)</sub>	Turn-Off Delay Time		_	44.3	-	1
		1		+		-

## Turn-Off Fall Time SOURCE-TO-DRAIN DIODE CHARACTERISTICS

t<sub>f</sub>

۱ <sub>S</sub>	Maximum Continuous Source-to-Drain Diode Forward Current		-	-	11	А
I <sub>SM</sub>	Maximum Pulsed Source-to-Drain Diode Forward Current		-	-	25	Α
V <sub>SD</sub>	Source-to-Drain Diode Forward Volt- age	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 5.5 A	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 V, I_{SD} = 2.75 A, di_F/$	-	170	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dt = 100 A/µs	-	1.5	-	μC

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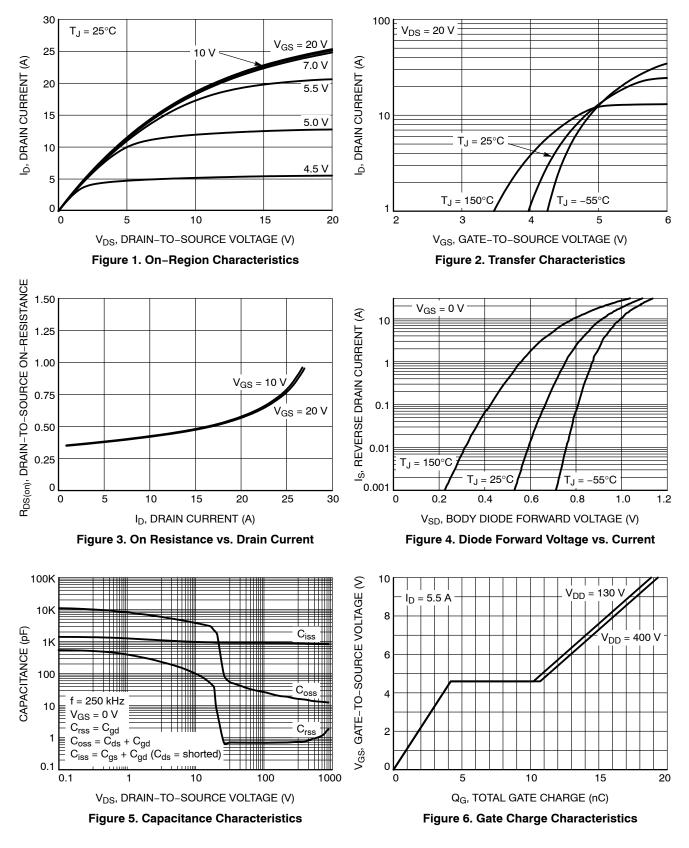
4.6

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

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#### **TYPICAL CHARACTERISTICS**



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## **TYPICAL CHARACTERISTICS**

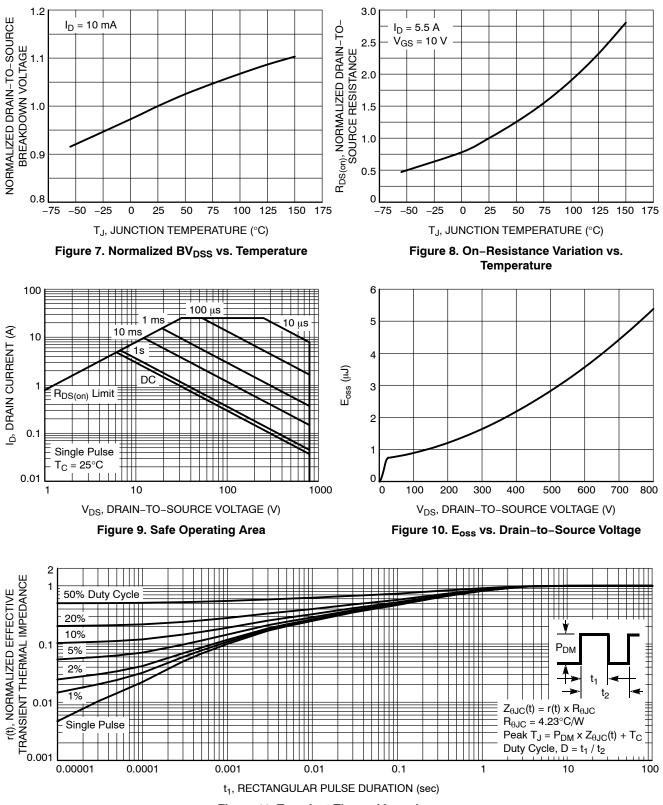
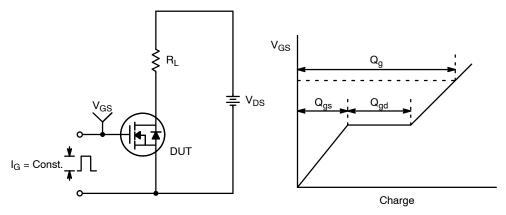


Figure 11. Transient Thermal Impedance

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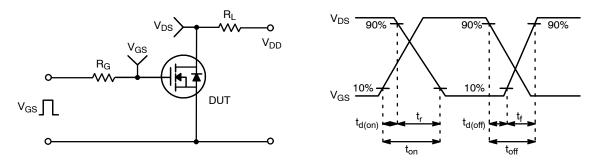


Figure 13. Resistive Switching Test Circuit & Waveforms

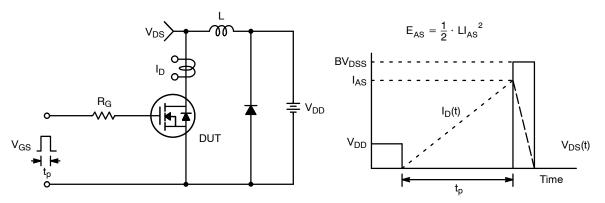
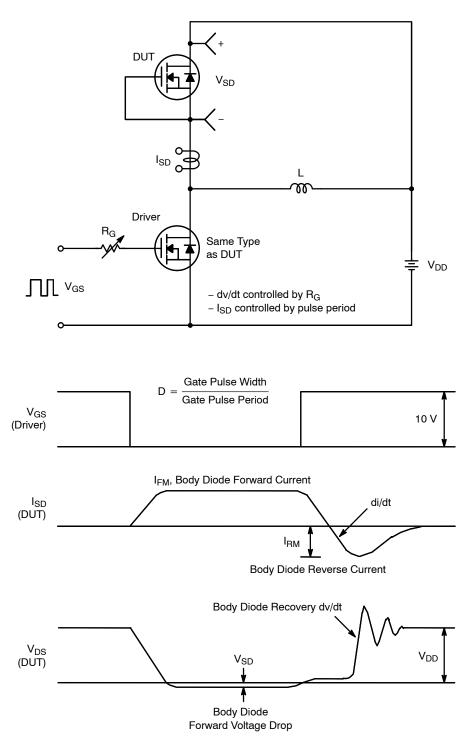
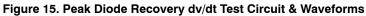


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

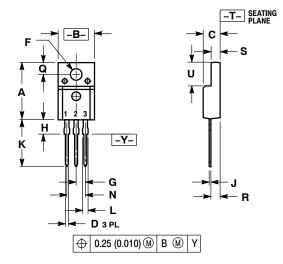




#### PACKAGE DIMENSIONS

## TO-220 FULLPAK CASE 221D-03

ISSUE K



NOTES:

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2. CONTROLLING DIMENSION: INCH 3. 221D-01 THRU 221D-02 OBSOLETE, NEW

221D-01 THRU 221D-0 STANDARD 221D-03.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.617	0.635	15.67	16.12
В	0.392	0.419	9.96	10.63
С	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100 BSC		2.54 BSC	
Н	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
Ν	0.200	BSC	5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

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